CLAIMS

[Claim 1] A polishing head for polishing a substrate, comprising:

a pressing member configured to press a polishing tape against the substrate;

an actuator configured to move the pressing member in a predetermined pressing direction and apply a pressing force to the pressing member; and

a tilt adjustment mechanism configured to adjust tilt of the pressing member with respect to the pressing direction, the tilt adjustment mechanism being configured to tilt the pressing member with respect to the pressing direction and maintain an angle of the tilted pressing member,

wherein the pressing member comprises O ring, or a linearly extending blade, or a curved blade.

[Claim 2] The polishing head according to claim 1, wherein the tilt adjustment mechanism has a first support shaft perpendicular to an advancing direction of the polishing tape and is configured to tilt the pressing member about the first support shaft.

[Claim 3] The polishing head according to claim 2, wherein the tilt adjustment mechanism comprises:

a base member supporting the first support shaft;

a tilt member coupled to the first support shaft and tiltable about the first support shaft; and

a plurality of screws that are screwed into a plurality of threaded holes formed in the tilt member, the plurality of screws being in contact with the base member.

[Claim 4] The polishing head according to claim 3, wherein the plurality of screws are disposed at both sides of the first support shaft.

[Claim 5] The polishing head according to claim 3 or 4, further comprising a

pressing-member holder that holds the pressing member, the tilt adjustment mechanism further including a second support shaft that is perpendicular to the first support shaft, the pressing-member holder being tiltable about the second support shaft.

[Claim 6] The polishing head according to claim 1, wherein the pressing member has at least one tape-pressing surface that extends obliquely with respect to an advancing direction of the polishing tape.

[Claim 7] A polishing apparatus comprising:

a substrate holder configured to hold a substrate; and

a polishing head of any one of claims 1 to 6 configured to polish the substrate.